

### **Amendments to the Specification:**

Please replace the existing Abstract and substitute the following in its place:

A method of forming an electronic component includes forming first and second conductive materials over a substrate, with the second material having a higher oxidation rate than an oxidation rate of the first material when exposed to a thermal oxidizing atmosphere. The first and second conductive materials are first etched to form a conductive component. The conductive component has opposing outer lateral edges of the first and second conductive materials which span between the opposing outer lateral edges. Second etching is conducted into both of the second material outer lateral edges to recess them inside of the first material outer lateral edges. After the second etching, the substrate is exposed to the thermal oxidizing atmosphere effective to grow an oxide layer over both of the outer lateral edges of the first and second conductive materials. Electronic components are disclosed and claimed independent of any method of manufacture.